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<u>Claims</u>

Please add the following claims 13-18:

- 13. An assembly as claimed in claim 1, wherein the optical transceiver module comprises a light emitting diode and a photodiode, packaged together with supporting circuitry to form a self-contained unit.
- 14. An assembly as claimed in claim 13, wherein the optical transceiver module comprises a first molded lens shape over the light emitting diode and a second molded lens shape over the photodiode.
- 15. An assembly as claimed in claim 13, wherein the optical transceiver module is an infrared transceiver module.
- 16. An assembly as claimed in claim 2, wherein the side surface of the planar circuit board is a multi-faceted surface bounding the recess on three sides and leaving a fourth side open.
- 17. An assembly as claimed in claim 16, wherein the optical transceiver module comprises a plurality of transceiver lenses which face outwards from the open side of the recess.
- 18. An assembly as claimed in claim 1, wherein the optical transceiver module is surface mounted on the extended portion of the substrate.